

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Priority Application Serial No. .... 09/714,714  
Priority Filing Date ..... November 15, 2000  
Inventor ..... Kardokus, J. et al  
Assignee ..... Honeywell International, Inc  
Priority Group Art Unit ..... 1742  
Priority Examiner ..... Ip, S  
Attorney's Docket No. .... JM34006 DIV  
Title: (As Amended) Methods of Forming Copper-Containing Sputtering Targets

2/A  
C.7.  
1/23/02

**PRELIMINARY AMENDMENT**

To: Box Patent Application  
Assistant Commissioner for Patents  
Washington, D.C. 20231

From: Jennifer J. Taylor, Ph.D. (Tel. 509-624-4276; Fax 509-838-3424)  
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**AMENDMENTS**

**In the Specification**

- Please replace the Title with the following new Title:  
K' --Methods of Forming Copper --Containing Sputtering Targets--

Before the "Background of the Invention" section, please add:

**RELATED PATENT DATA**

A<sup>2</sup> This patent resulted from a divisional application of U.S. Patent Application Serial  
No. 09/714,714; which is a continuation application of U.S. Patent Application Serial No.